

Advanced Power MOSFET

IRFW/IZ24A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- 175°C Operating Temperature
- Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 60V$
- Lower $R_{DS(on)}$: 0.050 Ω (Typ.)

$$BV_{DSS} = 60 V$$

$$R_{DS(on)} = 0.07 \Omega$$

$$I_D = 17 A$$

D²-PAK P-PAK



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current ($T_c=25^\circ C$)	17	A
	Continuous Drain Current ($T_c=100^\circ C$)	12	
I_{DM}	Drain Current-Pulsed ①	68	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy ②	149	mJ
I_{AR}	Avalanche Current ①	17	A
E_{AR}	Repetitive Avalanche Energy ①	4.4	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
P_D	Total Power Dissipation ($T_A=25^\circ C$)*	3.8	W
	Total Power Dissipation ($T_c=25^\circ C$)	44	W
	Linear Derating Factor	0.29	W/ $^\circ C$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +175	$^\circ C$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	3.43	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient *	—	40	
$R_{\theta JA}$	Junction-to-Ambient	—	62.5	

* When mounted on the minimum pad size recommended (PCB Mount).

SAMSUNG

ELECTRONICS

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	60	—	—	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	—	0.064	—	V/ $^\circ\text{C}$	$I_D=250\mu A$ See Fig 7
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS}=5V, I_D=250\mu A$
I_{GSS}	Gate-Source Leakage, Forward	—	—	100	nA	$V_{GS}=20V$
	Gate-Source Leakage, Reverse	—	—	-100		$V_{GS}=-20V$
I_{DSS}	Drain-to-Source Leakage Current	—	—	10	μA	$V_{DS}=60V$
		—	—	100		$V_{DS}=48V, T_C=150^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	—	—	0.07	Ω	$V_{GS}=10V, I_D=8.5A$ ④
g_{fs}	Forward Transconductance	—	10.8	—	S	$V_{DS}=30V, I_D=8.5A$ ④
C_{iss}	Input Capacitance	—	600	780	pF	$V_{GS}=0V, V_{DS}=25V, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	—	210	240		
C_{rss}	Reverse Transfer Capacitance	—	83	95		
$t_{d(on)}$	Turn-On Delay Time	—	13	30	ns	$V_{DD}=30V, I_D=17A,$ $R_G=18\Omega$ See Fig 13 ④⑤
t_r	Rise Time	—	19	40		
$t_{d(off)}$	Turn-Off Delay Time	—	46	100		
t_f	Fall Time	—	48	100		
Q_g	Total Gate Charge	—	24	32	nC	$V_{DS}=48V, V_{GS}=10V,$ $I_D=17A$ See Fig 6 & Fig 12 ④⑤
Q_{gs}	Gate-Source Charge	—	4.3	—		
Q_{gd}	Gate-Drain("Miller ") Charge	—	10.8	—		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	—	—	17	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	—	—	68		
V_{SD}	Diode Forward Voltage ④	—	—	1.5	V	$T_J=25^\circ\text{C}, I_S=17A, V_{GS}=0V$
t_{rr}	Reverse Recovery Time	—	60	—	ns	$T_J=25^\circ\text{C}, I_F=17A$
Q_{rr}	Reverse Recovery Charge	—	0.12	—	μC	$di_F/dt=100A/\mu s$ ④

Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② $L=0.6\text{mH}, I_{AS}=17A, V_{DD}=25V, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$
- ③ $I_{SD}\leq 17A, di/dt\leq 250A/\mu s, V_{DD}\leq BV_{DSS}$, Starting $T_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width = 250 μs , Duty Cycle $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

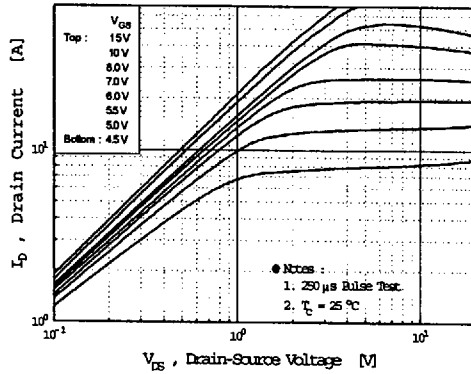


Fig 2. Transfer Characteristics

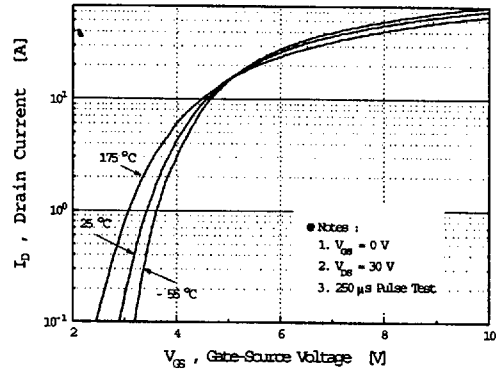


Fig 3. On-Resistance vs. Drain Current

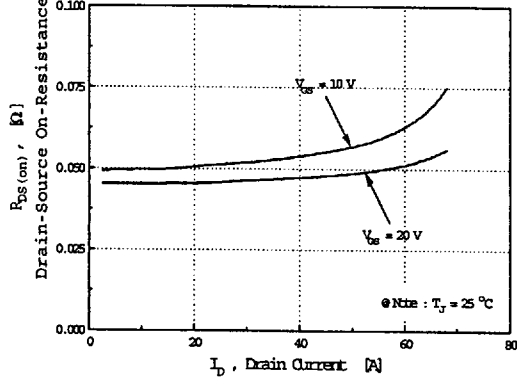


Fig 4. Source-Drain Diode Forward Voltage

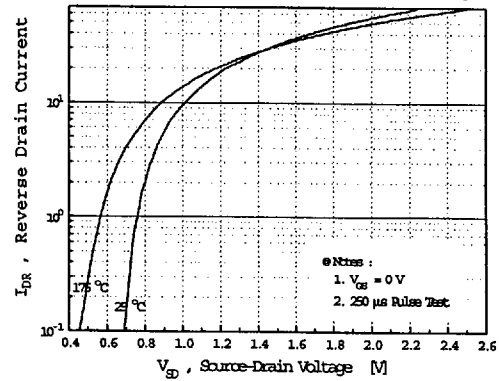


Fig 5. Capacitance vs. Drain-Source Voltage

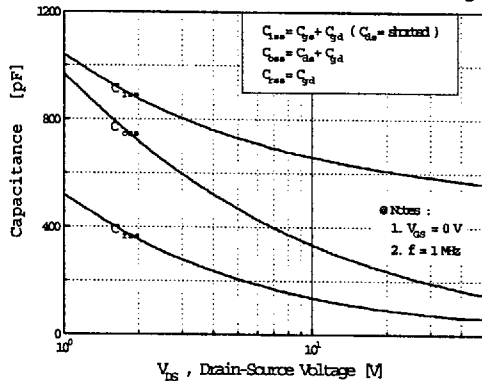
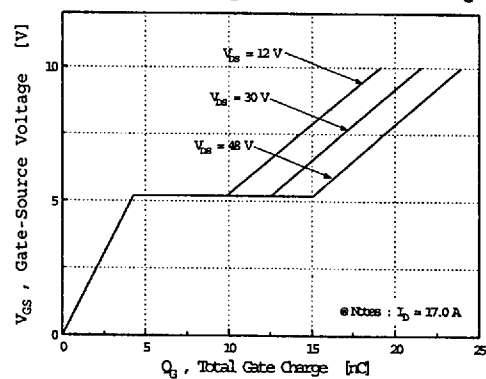


Fig 6. Gate Charge vs. Gate-Source Voltage



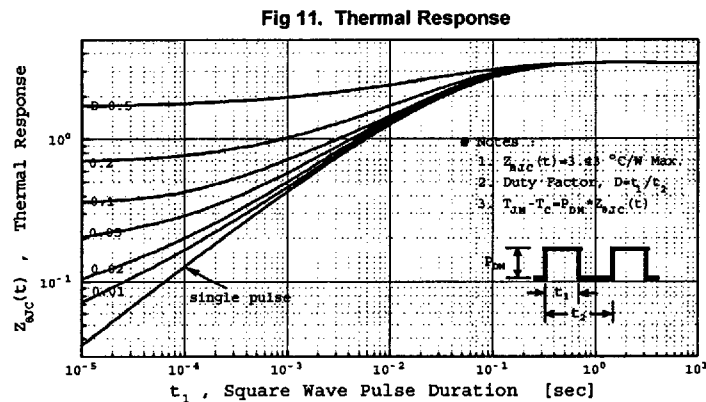
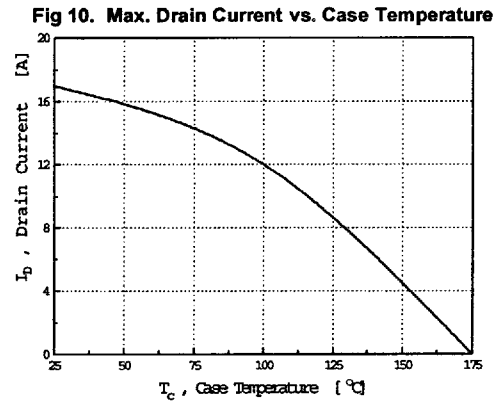
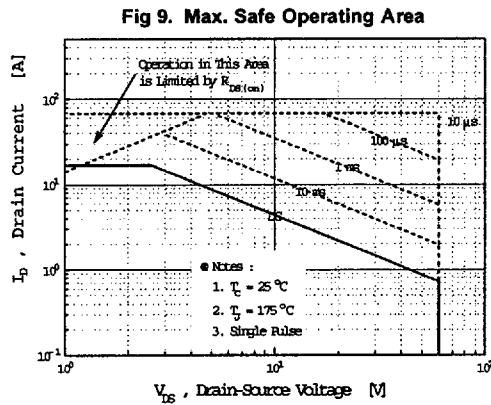
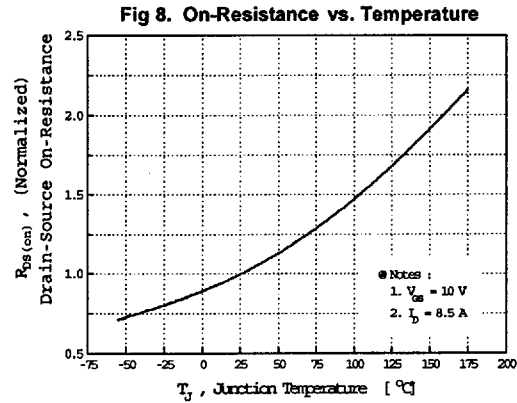
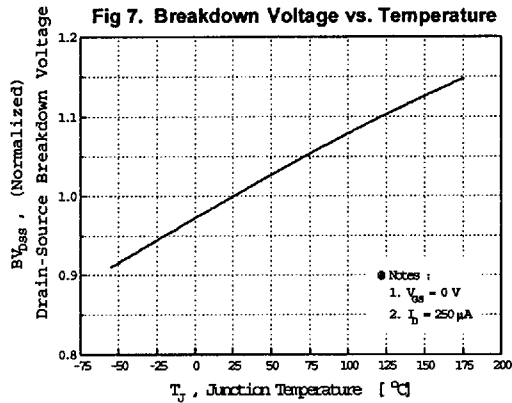


Fig 12. Gate Charge Test Circuit & Waveform

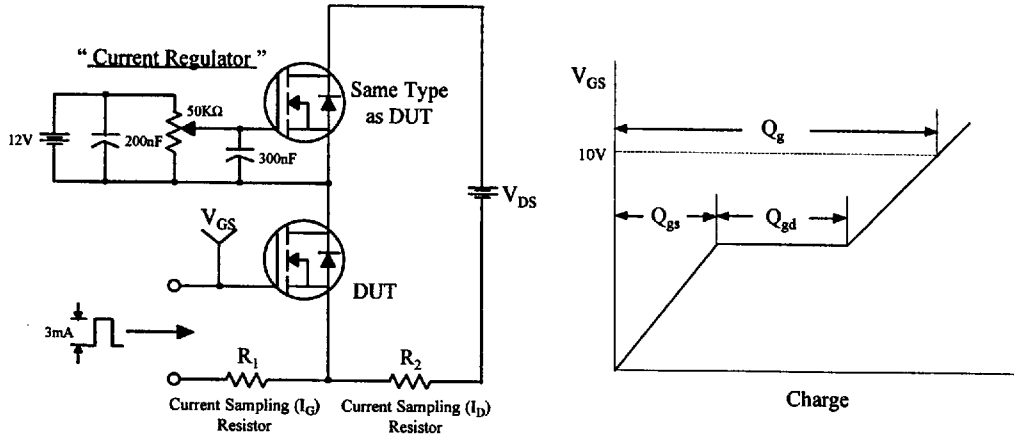


Fig 13. Resistive Switching Test Circuit & Waveforms

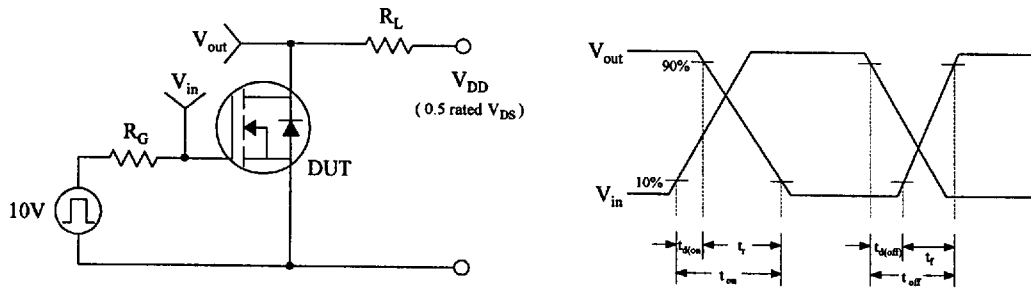


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

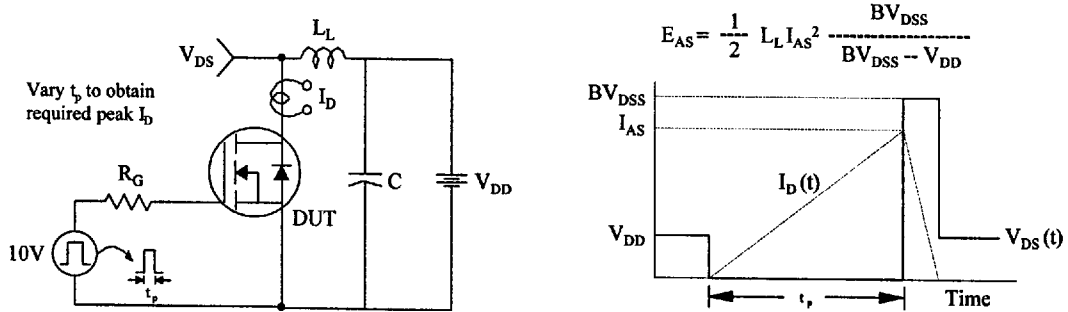


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

